

SEMICONDUCTOR PACKAGE INCLUDING STACKED CHIPS

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ABSTRACT OF THE DISCLOSURE

10 Semiconductor packages are disclosed. An exemplary
package includes horizontal leads each having a first side
and an opposite second side. The second side includes a
recessed horizontal surface. Two stacked semiconductor
chips are within the package and are electrically
interconnected in a flip chip style. One chip extends over
the first side of the leads and is electrically connected
15 thereto. The chips are encapsulated in a package body
formed of an encapsulating material. The recessed
horizontal surface of the leads is covered by the
encapsulating material, and a portion of the second side of
each lead is exposed at an exterior surface of the package
20 body as an input/output terminal. A surface of one or both
chips may be exposed. The stack of chips may be supported
on the first side of the leads or on a chip mounting plate.